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Alpha and Omega Semiconductor Rolls Out Family of Devices in Molded Chip Scale Package

A breakaway technological innovation for space-constrained portable devices

SUNNYVALE, Calif., Dec. 18, 2012 – Alpha and Omega Semiconductor Limited (AOS) (Nasdaq: AOSL), a designer, developer and global supplier of a broad range of power semiconductors, today released a family of low on-resistance 8V, 20V, and 30V MOSFETs in the ultra-thin molded chip scale package (MCSP). The MCSP devices feature a maximum height of only 0.3mm to provide a perfect solution for ultra-slim designs. Compared to existing CSP solutions the new family reduces package height by 50% and improves the overall mechanical robustness of the package. The noteworthy performance enhancements offered by the MCSP technology, make these new devices ideal for the latest ultra-portable applications such as smart phones, tablet PCs, Ultrabooks, and other mobile hand-held devices.

The proprietary MCSP packaging technology encapsulates AOS's low on-resistance MOSFET silicon in a protective Green (halogen-free) molding compound. The resulting product provides a thinner and more robust structure to solve die chipping and placement issues associated with standard CSP products. The new family of MCSP devices offers major performance benefits and at the same time can easily replace industry standard CSP devices by offering the same footprint, pin-out, and pitch.

"The new family of molded chip scale devices, offer our customers an unparalleled solution for space and height constrained ultra-portable designs. The combination of AOS's advanced packaging and MOSFET silicon technologies allow designers to keep pushing the space and height limits of advanced ultra-portable applications." said Peter Wilson, Director of Low Voltage MOSFETs at AOS.

The new portfolio of MCSP products includes n- and p-channel devices with V_{DS} ratings from 8V to 30V in package options of 0.97mm x 0.97mm and 1.57mm x 1.57mm. AOC2414, AOC2421, and AOC2422 have guaranteed ultra-low on-resistance rated at 1.2V_{GS} which helps designers to simplify drive circuitry, lower power consumption and extend battery life in ultra-portable applications.

Device Specification Table

Part Number	Size (mm)	Ch.	V_{DS} (V)	V_{GS} (V)	$R_{DS(ON)MAX}$ (mOhms)						Q_g (typ) (nC)	I_D @ T_A = 25°C (A)
					@ 10V	@ 4.5V	@ 2.5V	@ 1.8V	@ 1.5V	@ 1.2V		
AOC2403	0.97x0.97	P-	-20	±8		95	115	150	200		4.8	-1.8
AOC2421	0.97x0.97	P-	-8	±5			62	72	85	115	7.5	-2.5
AOC2422	0.97x0.97	N-	8	±5			33	38	43	58	9.5	3.5
AOC2423	0.97x0.97	P-	-20	±12	80	95	120				5	-2
AOC2401	1.57 x1.57	P-	-30	±12	41	47	58				13.5	-3
AOC2412	1.57 x1.57	N-	20	±8		23	26	30			21.5	4.5
AOC2414	1.57 x1.57	N-	8	±5			19	21	24	29	21.5	4.5
AOC2415	1.57 x1.57	P-	-20	±8		33	38	45	54		19	-3.5
AOC2417	1.57 x1.57	P-	-20	±12	32	38	50				14	-3.5

Pricing and Availability
All mentioned devices are available in production quantities with a lead-time of 12 weeks. The unit price for 1,000 pieces ranges from $0.23 to $0.30, depending on the device. Please contact your local AOS sales representative for full details.

About AOS
Alpha and Omega Semiconductor Limited, or AOS, is a designer, developer and global supplier of a broad range of power semiconductors, including a wide portfolio of Power MOSFET, IGBT and Power IC products. AOS has developed extensive intellectual property and technical knowledge that encompasses the latest advancements in the power semiconductor industry. AOS differentiates itself by integrating its Discrete and IC semiconductor process technology, product design, and advanced packaging know-how to develop high performance power management solutions. AOS's portfolio of products targets high-volume applications, including portable computers, flat panel TVs, LED lighting, smart phones, battery packs, consumer and industrial motor controls and power supplies for TVs, computers, servers and telecommunications equipment. For more information, please visit www.aosmd.com.

Forward Looking Statements
This press release contains forward-looking statements that are based on current expectations, estimates, forecasts and projections of future performance based on management's judgment, beliefs, current trends and anticipated product performance. These forward-looking statements include, without limitation, references to the efficiency and capability of new products, and the potential to expand into new markets. Forward looking statements involve risks and uncertainties that may cause actual results to differ materially from those contained in the forward-looking statements. These factors include, but are not limited to, the actual product performance in volume production, the quality and reliability of the product, our ability to achieve design wins, the general business and economic conditions, the state of the semiconductor industry, and other risks as described in the Company's annual report and other filings with the U.S. Securities and Exchange Commission. Although the Company believes that the expectations reflected in the forward looking statements are reasonable, it cannot guarantee future results, level of activity, performance, or achievements. You should not place undue reliance on these forward-looking statements. All information provided in this press release is as of today's date, unless otherwise stated, and AOS undertakes no duty to update such information, except as required under applicable law.

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